

AMENDMENTS TO THE SPECIFICATION

Please replace the first paragraph on page 1 after the heading “CROSS-REFERENCE TO RELATED APPLICATIONS” with the following:

“This application is a continuation of Application Serial No. 09/697,344 entitled, “A Light-Emitting Panel and a Method for Making,” filed October 27, 2000. Also referenced hereby are the following applications which are incorporated herein by reference in their entireties: United States Patent Application No. 09/697,358 entitled *A Micro-Component for Use in a Light-Emitting Panel* filed October 27, 2000; United States Patent Application No. 09/697,498 entitled *A Method for Testing a Light-Emitting Panel and the Components Therein* filed October 27, 2000; United States Patent Application No. 09/697,345 entitled *A Method and System for Energizing a Micro-Component In a Light-Emitting Panel* filed October 27, 2000; and United States Patent Application No. 09/697,346 entitled *A Socket for Use in a Light-Emitting Panel* filed October 27, 2000.”

Please replace the paragraph beginning on page 22, line 14 and ending on page 23, line 17 with the following two paragraphs:

“The specification, above, has described, among other things, various components of a light-emitting panel and methodologies to make those components and to make a light-emitting panel. In an embodiment of the present invention, it is contemplated that those components may be manufactured and those methods for making may be accomplished as part of web fabrication process for manufacturing light-emitting panels. In another embodiment of the present invention, a web fabrication process for manufacturing light-emitting panels includes the steps of providing a first substrate, disposing micro-components on the first substrate, disposing a second substrate on the

first substrate so that the micro-components are sandwiched between the first and second substrates, and dicing the first and second substrate “sandwich” to form individual light-emitting panels. In another embodiment, the first and second substrates are provided as rolls of material. A plurality of sockets may either be preformed on the first substrate or may be formed in and/or on the first substrate as part of the web fabrication process. Likewise, the first and second substrates may be preformed so that the first substrate, the second substrate or both substrates include a plurality of electrodes. Alternatively, a plurality of electrodes may be disposed on or within the first substrate, on or within the second substrate, or on and within both the first substrate and second substrate as part of the web fabrication process. It should be noted that where suitable, fabrication steps may be performed in any order. It should also be noted that the micro-components may be preformed or may be formed as part of the web fabrication process. In another embodiment, the web fabrication process is performed as a continuous high-speed inline process with the ability to manufacture light-emitting panels at a rate faster than light-emitting panels manufactured as part of batch process.

As shown in Figs. 12 and 13, in an embodiment of the present invention, the web fabrication process includes the following process steps: a micro-component forming process 800 for forming the micro-component shells and filling the micro-components with plasma-forming gas; a micro-component coating process 810 for coating the micro-components with phosphor or any other suitable coatings and producing a plurality of coated and filled micro-components 400; a circuit and electrode printing process 820 for printing at least one electrode and any needed driving and control circuitry on a first substrate 420; a patterning process 840 for patterning a plurality of cavities on a first substrate to form a plurality of sockets 430; a micro-component placement process 850 for properly placing at least one micro-component in each socket 430; an electrode printing process 860 for printing, if required, at least one electrode on a second substrate 410; a second substrate application and alignment process 870 for aligning the second substrate over the first substrate 440 so that the micro-components are sandwiched between the first substrate and the second substrate 450; and a panel dicing process 880 for dicing the first and second substrates 450 to form individual light-emitting panels 460.”